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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

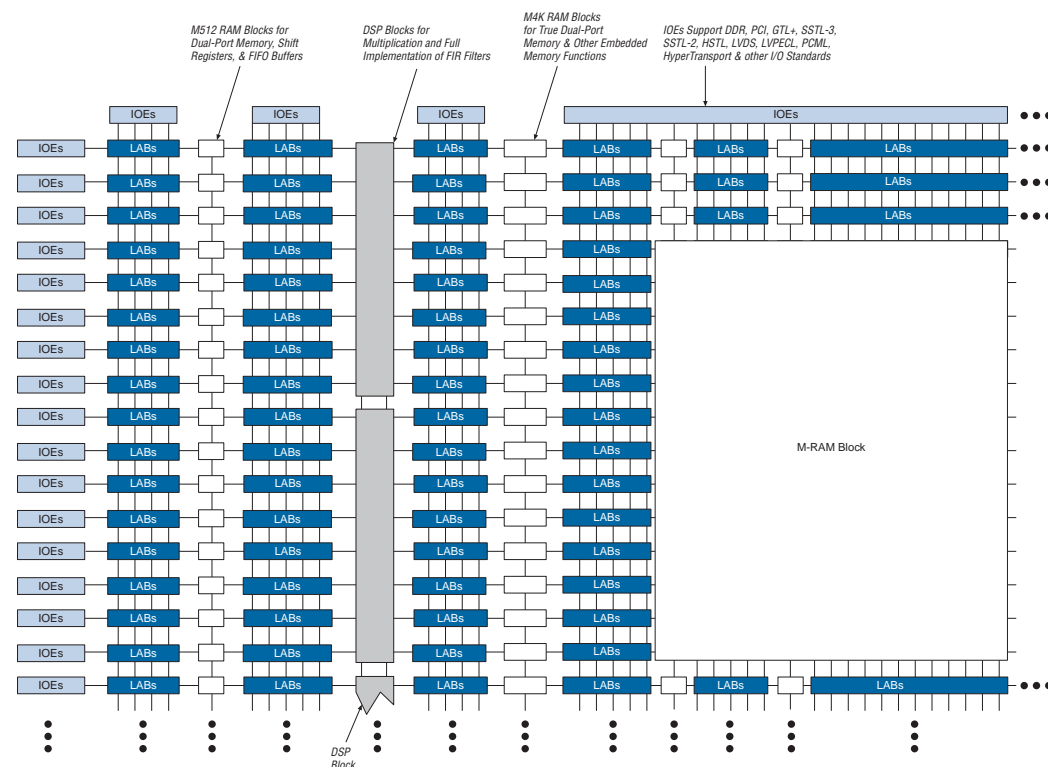
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

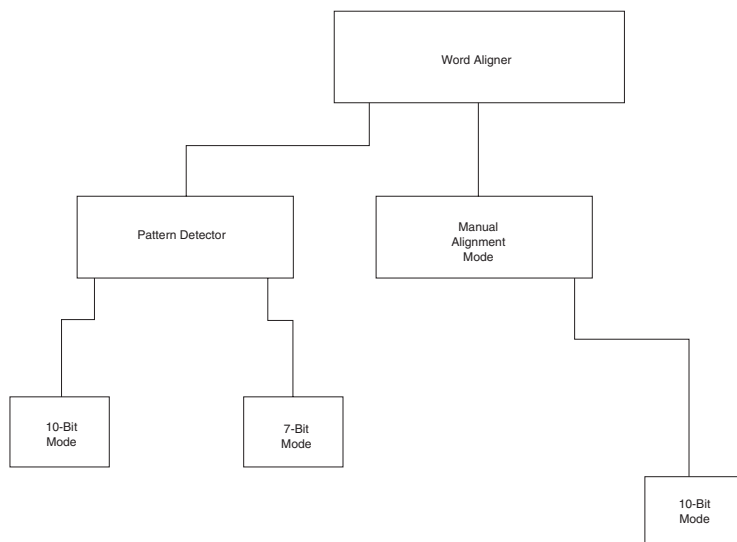
Product Status	Obsolete
Number of LABs/CLBs	1057
Number of Logic Elements/Cells	10570
Total RAM Bits	920448
Number of I/O	362
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/ep1sgx10df672c6">https://www.e-xfl.com/product-detail/intel/ep1sgx10df672c6</a>

**Figure 1–2. Stratix GX Block Diagram**

The number of M512 RAM, M4K RAM, and DSP blocks varies by device along with row and column numbers and M-RAM blocks. [Table 1–5](#) lists the resources available in Stratix GX devices.

**Table 1–5. Stratix GX Device Resources**

Device	M512 RAM Columns/Blocks	M4K RAM Columns/Blocks	M-RAM Blocks	DSP Block Columns/Blocks	LAB Columns	LAB Rows
EP1SGX10	4 / 94	2 / 60	1	2 / 6	40	30
EP1SGX25	6 / 224	3 / 138	2	2 / 10	62	46
EP1SGX40	8 / 384	3 / 183	4	2 / 14	77	61

**Figure 2–17. Word Aligner in 10-Bit Mode**

In the 10-bit mode, the word aligner automatically aligns the user's predefined 10-bit alignment pattern. The pattern detector can detect the full 10-bit pattern or only the lower seven bits of the pattern. The word aligner and pattern detector detect both the positive and the negative disparity of the pattern. A user-controlled enable port is available for the word aligner.

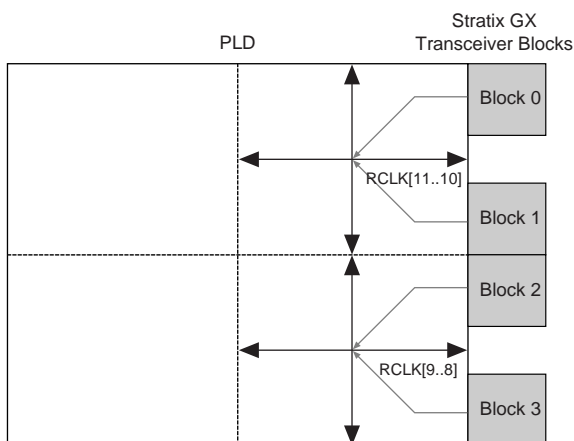
The 10-bit mode is available only for the Custom mode.

Figure 2–18 shows the word aligner in XAUI mode.

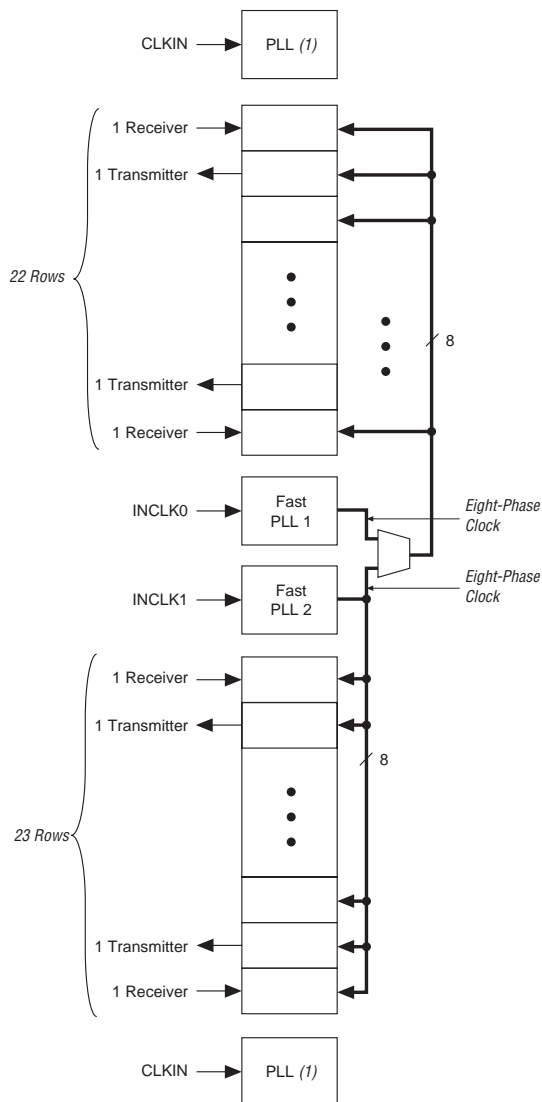
The receiver PLL can also drive the fast regional, regional clocks, and local routing adjacent to the associated transceiver block. Figures 2–28 through 2–31 show which fast regional and regional clock resource can be used by the recovered clock.

In the EP1SGX25 device, the receiver PLL recovered clocks from transceiver blocks 0 and 1 drive  $RCLK[1..0]$  while transceiver blocks 2 and 3 drive  $RCLK[7..6]$ . The regional clocks feed logic in their associated regions.

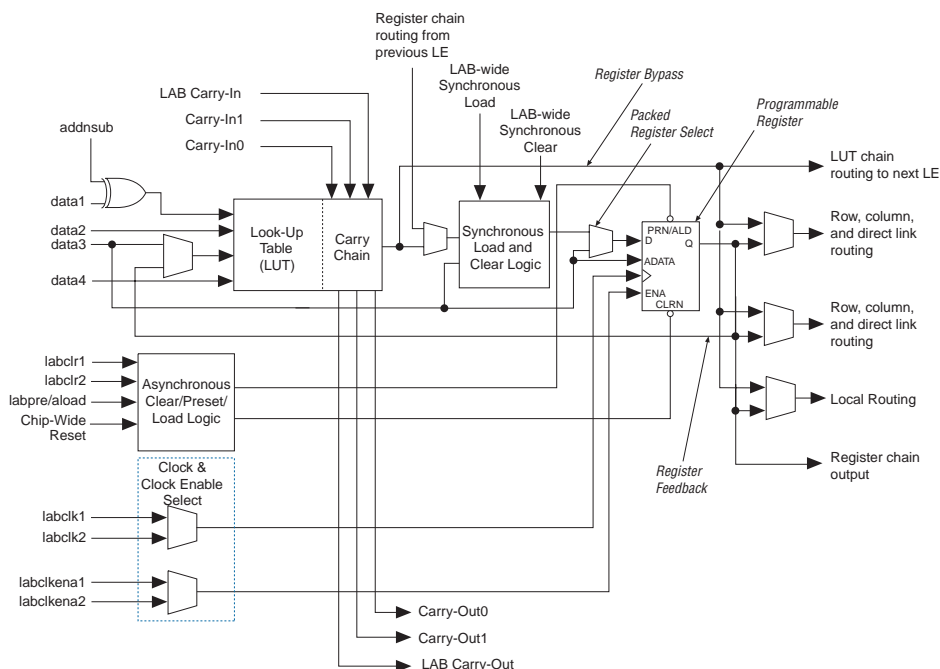
**Figure 2–28. EP1SGX25 Receiver PLL Recovered Clock to Regional Clock Connection**



In addition, the receiver PLL's recovered clocks can drive fast regional lines (FCLK) as shown Figure 2–29. The fast regional clocks can feed logic in their associated regions.

**Figure 3–7. PLL & Channel Layout in EP1SGX40 Devices** *Notes (1), (2), (3)***Notes to Figure 3–7:**

- (1) Corner PLLs do not support DPA.
- (2) Not all eight phases are used by the receiver channel or transmitter channel in non-DPA mode.
- (3) The center PLLs can only clock 20 transceivers in either direction. Using Fast PLL2, you can clock a total of 40 transceivers, 20 in each direction.

**Figure 4–4. Stratix GX LE**

Each LE's programmable register can be configured for D, T, JK, or SR operation. Each register has data, true asynchronous load data, clock, clock enable, clear, and asynchronous load/preset inputs. Global signals, general-purpose I/O pins, or any internal logic can drive the register's clock and clear control signals. Either general-purpose I/O pins or internal logic can drive the clock enable, preset, asynchronous load, and asynchronous data. The asynchronous load data input comes from the data3 input of the LE. For combinatorial functions, the register is bypassed and the output of the LUT drives directly to the outputs of the LE.

Each LE has three outputs that drive the local, row, and column routing resources. The LUT or register output can drive these three outputs independently. Two LE outputs drive column or row and direct link routing connections and one drives local interconnect resources. This allows the LUT to drive one output while the register drives another output. This feature, called register packing, improves device utilization because the device can use the register and the LUT for unrelated functions. Another special packing mode allows the register output to feed back into the LUT of the same LE so that the register is packed with

its own fan-out LUT. This provides another mechanism for improved fitting. The LE can also drive out registered and unregistered versions of the LUT output.

## LUT Chain & Register Chain

In addition to the three general routing outputs, the LEs within an LAB have LUT chain and register chain outputs. LUT chain connections allow LUTs within the same LAB to cascade together for wide input functions. Register chain outputs allow registers within the same LAB to cascade together. The register chain output allows an LAB to use LUTs for a single combinatorial function and the registers to be used for an unrelated shift register implementation. These resources speed up connections between LABs while saving local interconnect resources. See [“MultiTrack Interconnect” on page 4–11](#) for more information on LUT chain and register chain connections.

## addnsub Signal

The LE’s dynamic adder/subtractor feature saves logic resources by using one set of LEs to implement both an adder and a subtractor. This feature is controlled by the LAB-wide control signal `addnsub`. The `addnsub` signal sets the LAB to perform either  $A + B$  or  $A - B$ . The LUT computes addition, and subtraction is computed by adding the two’s complement of the intended subtractor. The LAB-wide signal converts to two’s complement by inverting the B bits within the LAB and setting carry-in = 1 to add one to the least significant bit (LSB). The LSB of an adder/subtractor must be placed in the first LE of the LAB, where the LAB-wide `addnsub` signal automatically sets the carry-in to 1. The Quartus II Compiler automatically places and uses the adder/subtractor feature when using adder/subtractor parameterized functions.

## LE Operating Modes

The Stratix GX LE can operate in one of the following modes:

- Normal mode
- Dynamic arithmetic mode

Each mode uses LE resources differently. In each mode, eight available inputs to the LE—the four data inputs from the LAB local interconnect; `carry-in0` and `carry-in1` from the previous LE; the LAB carry-in from the previous carry-chain LAB; and the register chain connection—are directed to different destinations to implement the desired logic function. LAB-wide signals provide clock, asynchronous clear, asynchronous preset load, synchronous clear, synchronous load, and

LAB and do not drive directly to LAB local interconnects. R24 row interconnects drive LAB local interconnects via R4 and C4 interconnects. R24 interconnects can drive R24, R4, C16, and C4 interconnects.

The column interconnect operates similarly to the row interconnect and vertically routes signals to and from LABs, TriMatrix memory, DSP blocks, and IOEs. Each column of LABs is served by a dedicated column interconnect, which vertically routes signals to and from LABs, TriMatrix memory and DSP blocks, and horizontal IOEs. These column resources include:

- LUT chain interconnects within an LAB
- Register chain interconnects within an LAB
- C4 interconnects traversing a distance of four blocks in up and down direction
- C8 interconnects traversing a distance of eight blocks in up and down direction
- C16 column interconnects for high-speed vertical routing through the device

Stratix GX devices include an enhanced interconnect structure within LABs for routing LE output to LE input connections faster using LUT chain connections and register chain connections. The LUT chain connection allows the combinatorial output of an LE to directly drive the fast input of the LE right below it, bypassing the local interconnect. These resources can be used as a high-speed connection for wide fan-in functions from LE 1 to LE 10 in the same LAB. The register chain connection allows the register output of one LE to connect directly to the register input of the next LE in the LAB for fast shift registers. The Quartus II Compiler automatically takes advantage of these resources to improve utilization and performance. [Figure 4–9](#) shows the LUT chain and register chain interconnects.



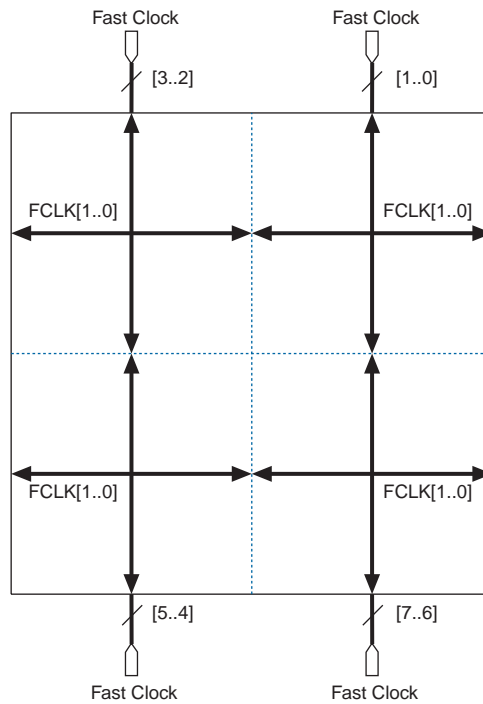
Table 4–11 shows the input and output data signal connections for the column units (B1 to B6 and A1 to A6). It also shows the address and control signal input connections to the row units (R1 to R11).

<b>Table 4–11. M-RAM Row &amp; Column Interface Unit Signals</b>		
<b>Unit Interface Block</b>	<b>Input Signals</b>	<b>Output Signals</b>
R1	addressa[7..0]	
R2	addressa[15..8]	
R3	byte_enable_a[7..0] renwe_a	
R4	-	
R5	-	
R6	clock_a clocken_a clock_b clocken_b	
R7	-	
R8	-	
R9	byte_enable_b[7..0] renwe_b	
R10	addressb[15..8]	
R11	addressb[7..0]	
B1	datain_b[71..60]	dataout_b[71..60]
B2	datain_b[59..48]	dataout_b[59..48]
B3	datain_b[47..36]	dataout_b[47..36]
B4	datain_b[35..24]	dataout_b[35..24]
B5	datain_b[23..12]	dataout_b[23..12]
B6	datain_b[11..0]	dataout_b[11..0]
A1	datain_a[71..60]	dataout_a[71..60]
A2	datain_a[59..48]	dataout_a[59..48]
A3	datain_a[47..36]	dataout_a[47..36]
A4	datain_a[35..24]	dataout_a[35..24]
A5	datain_a[23..12]	dataout_a[23..12]
A6	datain_a[11..0]	dataout_a[11..0]

## **Independent Clock Mode**

The memory blocks implement independent clock mode for true dual-port memory. In this mode, a separate clock is available for each port (ports A and B). Clock A controls all registers on the port A side, while clock B controls all registers on the port B side. Each port, A and B, also supports independent clock enables and asynchronous clear signals for port A and B registers. [Figure 4–23](#) shows a TriMatrix memory block in independent clock mode.

**Figure 4–43. EP1SGX25 & EP1SGX10 Device Fast Clock Pin Connections to Fast Regional Clocks**



**Table 4–18. Stratix GX Enhanced PLL & Fast PLL Features (Part 2 of 2)** *Notes (1)–(8)*

Feature	Enhanced PLL	Fast PLL
Number of external clock outputs	Four differential/eight singled-ended or one single-ended (6)	(7)
Number of feedback clock inputs	4 (8)	

**Notes to Table 4–18:**

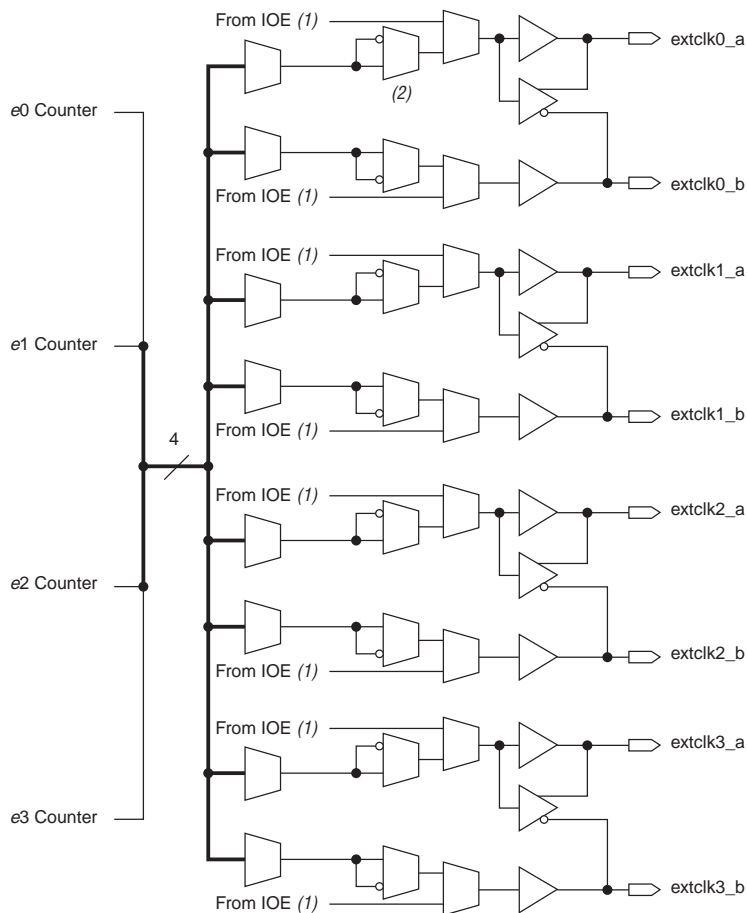
- (1) The maximum count value is 1024, with a 50% duty cycle setting on the counter. The maximum count value for any other duty cycle setting is 512.
- (2) For fast PLLs, *m* and post-scale counters range from 1 to 32.
- (3) The smallest phase shift is determined by the VCO period divided by 8.
- (4) For degree increments, Stratix GX devices can shift all output frequencies in increments of at least 45°. Smaller degree increments are possible depending on the frequency and divide parameters.
- (5) PLLs 7 and 8 have two output ports per PLL. PLLs 1 and 2 have three output ports per PLL.
- (6) Every Stratix GX device has two enhanced PLLs (PLLs 5 and 6) with eight single-ended or four differential outputs each. Two additional enhanced PLLs (PLLs 11 and 12) in EP1SGX40 devices each have one single-ended output.
- (7) Fast PLLs can drive to any I/O pin as an external clock. For high-speed differential I/O pins, the device uses a data channel to generate `txclkout`.
- (8) Every Stratix GX device has two enhanced PLLs with one single-ended or differential external feedback input per PLL.

Figure 4–48 shows a top-level diagram of the Stratix GX device and the PLL floorplan.

## External Clock Outputs

Enhanced PLLs 5 and 6 each support up to eight single-ended clock outputs (or four differential pairs). See [Figure 4–54](#).

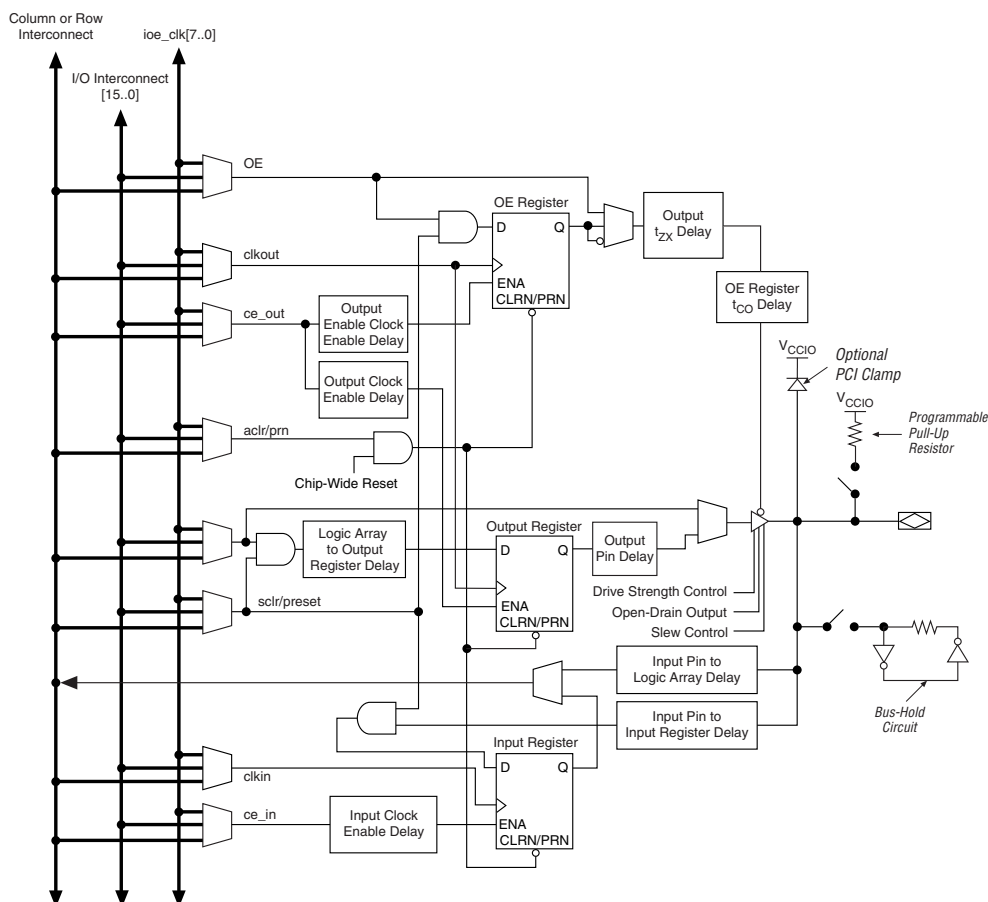
**Figure 4–54. External Clock Outputs for PLLs 5 & 6**



### Notes to [Figure 4–54](#):

- (1) Each external clock output pin can be used as a general purpose output pin from the logic array. These pins are multiplexed with IOE outputs.
- (2) Two single-ended outputs are possible per output counter—either two outputs of the same frequency and phase or one shifted 180°.

Any of the four external output counters can drive the single-ended or differential clock outputs for PLLs 5 and 6. This means one counter or frequency can drive all output pins available from PLL 5 or PLL 6. Each

**Figure 4–63. Stratix GX IOE in Bidirectional I/O Configuration** *Note (1)***Note to Figure 4–63:**

(1) All input signals to the IOE can be inverted at the IOE.

The Stratix GX device IOE includes programmable delays that can be activated to ensure zero hold times, input IOE register-to-logic array register transfers, or logic array-to-output IOE register transfers.

A path in which a pin directly drives a register may require the delay to ensure zero hold time, whereas a path in which a pin drives a register through combinatorial logic may not require the delay. Programmable delays exist for decreasing input-pin-to-logic-array and IOE input register delays. The Quartus II Compiler can program these delays to automatically minimize setup time while providing a zero hold time.

**Table 4–28. I/O Support by Bank (Part 2 of 2)**

I/O Standard	Top & Bottom Banks (3, 4, 7 & 8)	Left Banks (1 & 2)	Enhanced PLL External Clock Output Banks (9, 10, 11 & 12)
SSTL-3 class II	✓	✓	✓
AGP (1× and 2×)	✓		✓
CTT	✓	✓	✓

Each I/O bank has its own  $V_{CCIO}$  pins. A single device can support 1.5-, 1.8-, 2.5-, and 3.3-V interfaces; each bank can support a different standard independently. Each bank also has dedicated VREF pins to support any one of the voltage-referenced standards (such as SSTL-3) independently.

Each I/O bank can support multiple standards with the same  $V_{CCIO}$  for input and output pins. Each bank can support one voltage-referenced I/O standard. For example, when  $V_{CCIO}$  is 3.3 V, a bank can support LVTTTL, LVCMOS, 3.3-V PCI, and SSTL-3 for inputs and outputs.

### Differential On-Chip Termination

Stratix GX devices provide differential on-chip termination (LVDS I/O standard) to reduce reflections and maintain signal integrity. Differential on-chip termination simplifies board design by minimizing the number of external termination resistors required. Termination can be placed inside the package, eliminating small stubs that can still lead to reflections. The internal termination is designed using transistors in the linear region of operation.

Stratix GX devices support internal differential termination with a nominal resistance value of 137.5  $\Omega$  for LVDS input receiver buffers. LVPECL signals require an external termination resistor. [Figure 4–70](#) shows the device with differential termination.

**Table 6–7. Stratix GX Transceiver Block AC Specification (Part 3 of 7)**

Symbol / Description	Conditions	-5 Commercial Speed Grade (1)			-6 Commercial & Industrial Speed Grade (1)			-7 Commercial & Industrial Speed Grade (1)			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Sinusoidal jitter	f = 42.5 kHz at 1.0625 Gbps			1.5			1.5			1.5	UI
	f = 637 kHz at 1.0625 Gbps			0.1			0.1			0.1	UI
Deterministic jitter	2.125 Gbps			0.33			0.33			0.33	UI
Total jitter	2.125 Gbps			0.62			0.62			0.62	UI
Sinusoidal jitter	f = 85 kHz at 2.125 Gbps			1.5			1.5			1.5	UI
	f = 1,274 kHz at 2.125 Gbps			0.1			0.1			0.1	UI
<b>Serial Rapid I/O Receiver Jitter Tolerance using 8B/10B Encoded CJPAT</b> <i>Note (2)</i>											
Deterministic jitter	1.25 Gbps			0.45			0.45			0.45	UI
Total jitter	1.25 Gbps			0.71			0.71			0.71	UI
Deterministic jitter	2.5 Gbps			0.41			0.41			0.41	UI
Total jitter	2.5 Gbps			0.65			0.65			0.65	UI
Deterministic jitter	3.125 Gbps			0.36			0.36			N/A	UI
Total jitter	3.125 Gbps			0.60			0.60			N/A	UI
<b>SONET Receiver Jitter Tolerance using PRBS23</b> <i>Note (2)</i>											
Sinusoidal jitter	f = 6 kHz at 2.48832 Gbps			1.5			1.5			1.5	UI
	f = 1 MHz at 2.48832 Gbps			0.15			0.15			0.15	UI
<b>XAUI Receiver Jitter Tolerance using 8B/10B Encoded CJPAT</b> <i>Note (2)</i>											
Deterministic jitter	3.125 Gbps			0.37			0.37			N/A	UI
Total jitter	3.125 Gbps			0.65			0.65			N/A	UI



**Table 6–7. Stratix GX Transceiver Block AC Specification (Part 5 of 7)**

Symbol / Description	Conditions	-5 Commercial Speed Grade (1)			-6 Commercial & Industrial Speed Grade (1)			-7 Commercial & Industrial Speed Grade (1)			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Fibre Channel Transmitter Jitter using 8B/10B Encoded CRPAT      Note (9)											
Deterministic jitter	1.0625 Gbps Pre-emphasis = 0			0.09			0.09			0.09	UI
Total jitter	V <sub>OD</sub> = 1,200 mV			0.17			0.17			0.17	UI
Deterministic jitter	2.125 Gbps Pre-emphasis= 1			0.16			0.16			0.16	UI
Total jitter	V <sub>OD</sub> = 1,200 mV			0.33			0.33			0.33	UI
Serial Rapid I/O Short Run Transmitter Jitter using 8B/10B Encoded CRPAT      Note (9)											
Deterministic jitter	1.25 Gbps Pre-emphasis = 1			0.09			0.09			0.09	UI
Total jitter	V <sub>OD</sub> = 1,600 mV			0.17			0.17			0.17	UI
Deterministic jitter	2.5 Gbps Pre-emphasis = 1			0.15			0.15			0.15	UI
Total jitter	V <sub>OD</sub> = 800 mV			0.32			0.32			0.32	UI
Deterministic jitter	3.125 Gbps Pre-emphasis = 1			0.15			0.15			N/A	UI
Total jitter	V <sub>OD</sub> = 800 mV			0.32			0.32			N/A	UI
Serial Rapid I/O Long Run Transmitter Jitter using 8B/10B Encoded CRPAT      Note (9)											
Deterministic jitter	1.25 Gbps Pre-emphasis = 1			0.09			0.09			0.09	UI
Total jitter	V <sub>OD</sub> = 1,600 mV			0.17			0.17			0.17	UI
Deterministic jitter	2.5 Gbps Pre-emphasis = 2			0.18			0.18			0.18	UI
Total jitter	V <sub>OD</sub> = 1,400 mV			0.35			0.35			0.35	UI
Deterministic jitter	3.125 Gbps Pre-emphasis = 2			0.20			0.20			N/A	UI
Total jitter	V <sub>OD</sub> = 1,400 mV			0.37			0.37			N/A	UI
SONET Transmitter Jitter PRBS23      Note (9)											
Total jitter	2.48832 Gbps Pre-emphasis = 1			0.20			0.20			0.20	UI
	V <sub>OD</sub> = 800 mV										

**Table 6–35. Stratix GX Device Performance (Part 3 of 3)** *Notes (1), (2)*

Applications		Resources Used			Performance			
		LEs	TriMatrix Memory Blocks	DSP Blocks	-5 Speed Grade	-6 Speed Grade	-7 Speed Grade	Units
TriMatrix memory M-RAM block	True dual-port RAM 16K × 36 bit	0	1	0	269.83	237.69	206.82	MHz
	Single port RAM 32K × 18 bit	0	1	0	275.86	244.55	212.76	MHz
	Simple dual-port RAM 32K × 18 bit	0	1	0	275.86	244.55	212.76	MHz
	True dual-port RAM 32K × 18 bit	0	1	0	275.86	244.55	212.76	MHz
	Single port RAM 64K × 9 bit	0	1	0	287.85	253.29	220.36	MHz
	Simple dual-port RAM 64K × 9 bit	0	1	0	287.85	253.29	220.36	MHz
	True dual-port RAM 64K × 9 bit	0	1	0	287.85	253.29	220.36	MHz
DSP block	9 × 9-bit multiplier (3)	0	0	1	335.0	293.94	255.68	MHz
	18 × 18-bit multiplier (4)	0	0	1	278.78	237.41	206.52	MHz
	36 × 36-bit multiplier (4)	0	0	1	148.25	134.71	117.16	MHz
	36 × 36-bit multiplier (5)	0	0	1	278.78	237.41	206.52	MHz
	18-bit, 4-tap FIR filter	0	0	1	278.78	237.41	206.52	MHz
Larger Designs	8-bit, 16-tap parallel FIR filter	58	0	4	141.26	133.49	114.88	MHz
	8-bit, 1,024-point FFT function	870	5	1	261.09	235.51	205.21	MHz

**Notes to Table 6–35:**

- (1) These design performance numbers were obtained using the Quartus II software.
- (2) Numbers not listed will be included in a future version of the data sheet.
- (3) This application uses registered inputs and outputs.
- (4) This application uses registered multiplier input and output stages within the DSP block.
- (5) This application uses registered multiplier input, pipeline, and output stages within the DSP block.

**Table 6–53. Stratix GX Global Clock External I/O Timing Parameters (Part 2 of 2)** *Notes (1), (2)*

Symbol	Parameter	Conditions
$t_{INHPLL}$	Hold time for input or bidirectional pin using column IOE input register with global clock fed by enhanced PLL with default phase setting	
$t_{OUTCOPLL}$	Clock-to-output delay output or bidirectional pin using column IOE output register with global clock enhanced PLL with default phase setting	$C_{LOAD} = 10 \text{ pF}$

**Notes to Table 6–53:**

- (1) These timing parameters are sample-tested only.
- (2) These timing parameters are for column IOE pins. Row IOE pins are 100- to 250-ps slower depending on device, speed grade, and the specific parameter in question. You should use the Quartus II software to verify the external timing for any pin.

Tables 6–54 through 6–59 show the external timing parameters on column and row pins for EP1SGX10 devices.

**Table 6–54. EP1SGX10 Column Pin Fast Regional Clock External I/O Timing Parameters**

Symbol	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{INSU}$	2.245		2.332		2.666		ns
$t_{INH}$	0.000		0.000		0.000		ns
$t_{OUTCO}$	2.000	4.597	2.000	4.920	2.000	5.635	ns

**Table 6–55. EP1SGX10 Column Pin Regional Clock External I/O Timing Parameters**

Symbol	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{INSU}$	2.114		2.218		2.348		ns
$t_{INH}$	0.000		0.000		0.000		ns
$t_{OUTCO}$	2.000	4.728	2.000	5.078	2.000	6.004	ns
$t_{INSUPLL}$	1.035		0.941		1.070		ns
$t_{INHPLL}$	0.000		0.000		0.000		ns
$t_{OUTCOPLL}$	0.500	2.629	0.500	2.769	0.500	3.158	ns

**Table 6–71. EP1SGX40 Row Pin Global Clock External I/O Timing Parameters (Part 2 of 2)**

Symbol	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{OUTCO}}$	2.000	5.365	2.000	5.775	2.000	6.621	ns
$t_{\text{INSUPLL}}$	1.126		1.186		1.352		ns
$t_{\text{INHPLL}}$	0.000		0.000		0.000		ns
$t_{\text{OUTCOPLL}}$	0.500	2.304	0.500	2.427	0.500	2.765	ns

## External I/O Delay Parameters

External I/O delay timing parameters, both for I/O standard input and output adders and programmable input and output delays, are specified by speed grade, independent of device density.

Tables 6–72 through 6–77 show the adder delays associated with column and row I/O pins. If an I/O standard is selected other than LVTTTL 24 mA with a fast slew rate, add the selected delay to the external  $t_{\text{CO}}$  and  $t_{\text{SU}}$  I/O parameters.

**Table 6–72. Stratix GX I/O Standard Column Pin Input Delay Adders (Part 1 of 2)**

I/O Standard	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
LVC MOS		0		0		0	ps
3.3-V LVTTTL		0		0		0	ps
2.5-V LVTTTL		30		31		35	ps
1.8-V LVTTTL		150		157		180	ps
1.5-V LVTTTL		210		220		252	ps
GTL		220		231		265	ps
GTL+		220		231		265	ps
3.3-V PCI		0		0		0	ps
3.3-V PCI-X 1.0		0		0		0	ps
Compact PCI		0		0		0	ps
AGP 1×		0		0		0	ps
AGP 2×		0		0		0	ps
CTT		120		126		144	ps
SSTL-3 class I		–30		–32		–37	ps
SSTL-3 class II		–30		–32		–37	ps

Tables 6–78 and 6–79 show the adder delays for the column and row IOE programmable delays, respectively. These delays are controlled with the Quartus II software logic options listed in the Parameter column.

**Table 6–78. Stratix GX IOE Programmable Delays on Column Pins**

Parameter	Setting	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	
Decrease input delay to internal cells	Off		3,970		4,367		5,022	ps
	On		3,390		3,729		4,288	ps
	Small		2,810		3,091		3,554	ps
	Medium		212		224		257	ps
	Large		212		224		257	ps
Decrease input delay to input register	Off		3900		4,290		4,933	ps
	On		0		0		0	ps
Decrease input delay to output register	Off		1,240		1,364		1,568	ps
	On		0		0		0	ps
Increase delay to output pin	Off		0		0		0	ps
	On		377		397		456	ps
Increase delay to output enable pin	Off		0		0		0	ps
	On		338		372		427	ps
Increase output clock enable delay	Off		0		0		0	ps
	On		540		594		683	ps
	Small		1,016		1,118		1,285	ps
	Large		1,016		1,118		1,285	ps
Increase input clock enable delay	Off		0		0		0	ps
	On		540		594		683	ps
	Small		1,016		1,118		1,285	ps
	Large		1,016		1,118		1,285	ps
Increase output enable clock enable delay	Off		0		0		0	ps
	On		540		594		683	ps
	Small		1,016		1,118		1,285	ps
	Large		1,016		1,118		1,285	ps